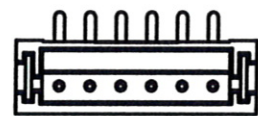
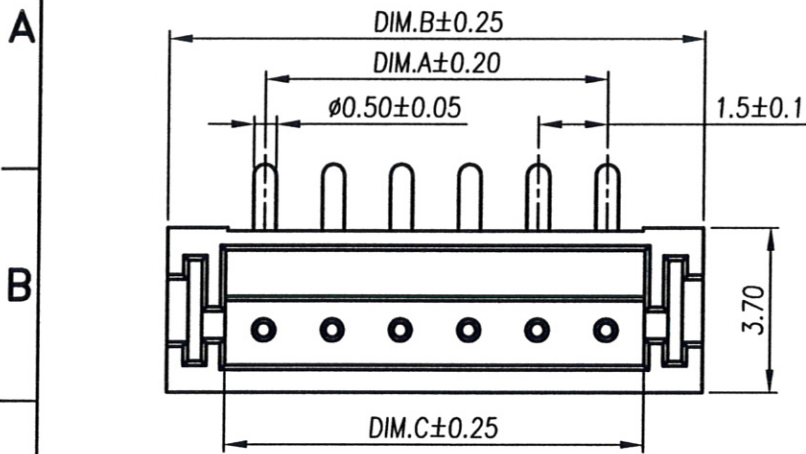


RoHS Compliant

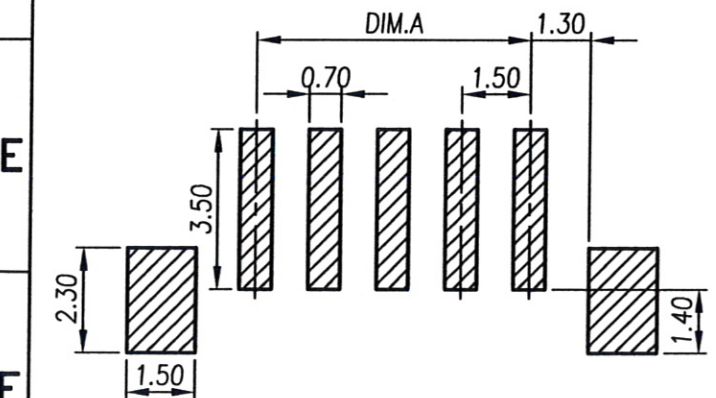
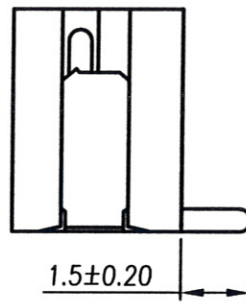
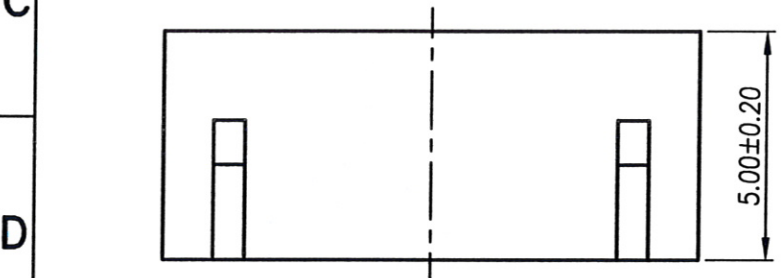
REV	MODIFICATION	DATE	DRAW
A4	Release To ECN20130203	2013.02.20	Seven
A5	Release To ECN20140702	2014.07.09	Seven
B0	Release To ECN20141206	2014.12.24	Michelle



Without Mylar



With Mylar



RECOMMENDED P.C.B LAYOUT

PIN	DIM.A	DIM.B	DIM.C
02	1.50	6.00	3.60
03	3.00	7.50	5.10
04	4.50	9.00	6.60
05	6.00	10.50	8.10
06	7.50	12.00	9.60
07	9.00	13.50	11.10
08	10.50	15.00	12.60
09	12.00	16.50	14.10
10	13.50	18.00	15.60
11	15.00	19.50	17.10
12	16.50	21.00	18.60
13	18.00	22.50	20.10

Specification

- 1.Current Rating:1A AC/DC
- 2.Voltage Rating:100V AC/DC
- 3.Contact Resistance:20mΩ Max.
- 4.Insulation Resistance:500MΩ Min. At DC 500V
- 5.Dielectric Withstanding Voltage:AC 500V/Minute
- 6.Operating Temperature:-25°C~+85°C



Material:

- 1.Housing:High Temperature Thermoplastic UL94V-0
- 2.Tab:Copper Alloy T=0.25mm
- 3.Contact Pin:Copper Alloy ø0.50mm
- 4.Mylar:Polyimide Film T=0.15mm



Finish:

- 1.Housing:Nature
- 2.Tab:Tin Plated Over Nickel
- 3.Contact Pin:Tin Plated Over Nickel
- 4.Mylar:Yellow

Part No.: AS06600 XX X X X 2

Number of Pin 02~13

Housing Material



A:HTN UL94V-0 Nature H.F


B:NY9T UL94V-0 Nature

Plating

- 1:Tab:Bright Tin Plated Over Nickel
- PIN:Bright Tin Plated Over Nickel
- 2:Tab:Bright Tin Plated Over Nickel
- PIN:Matte Tin Plated Over Nickel

- Packing
- 1:T&R
 - 4:TUBE
 - 8:T&R With MYLAR
 - A:TUBE With MYLAR





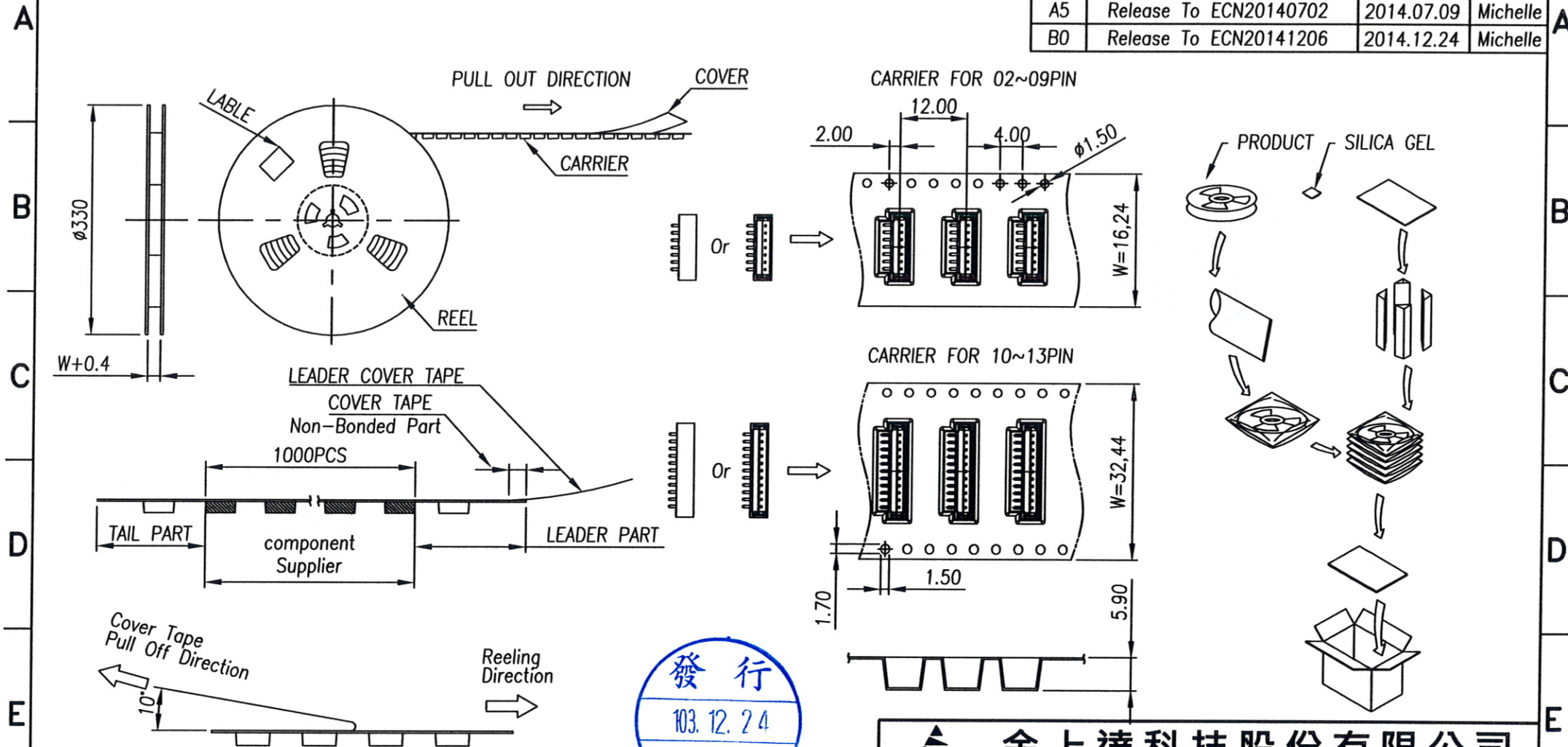
金上達科技股份有限公司

GOLDENSUNDA TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ.	TITLE: Wire To Board Wafer 1.50mm 180° SMT Single Row	
.x± 0.35	x.± 2'	APR. C.F.Liao 20141224	PART NO. AS06600XXXXX2	DWG NO. AS06600XXXXX2
.xx± 0.25	.x± 1'	CHK. Abel 20141224	UNITS: mm	CUSTOMER DRAWING
.xxx± 0.15	.xx± 0.5'	DRA. Michelle 20141224	SIZE: A4	SCALE 6:1
		SHEET 1 / 2	REV B0	V

RoHS Compliant


REV	MODIFICATION	DATE	DRAW
A4	Release To ECN20130203	2013.02.20	Seven
A5	Release To ECN20140702	2014.07.09	Michelle
B0	Release To ECN20141206	2014.12.24	Michelle



發行
103. 12. 24
文管中心

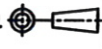
NO. OF PIN	W±0.3	PCS / REEL
02 ~ 04	16	1000
05 ~ 09	24	
10	32	
11 ~ 13	44	

NOTES:
1. Material : PS
2. Part No.: AS06600XXXX12 & AS06600XXXX82



金上達科技股份有限公司

GOLDENSUNDA TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ. 	TITLE: Wire To Board Wafer 1.50mm 180° SMT Single Row	
.x± 0.35	.x'± 2'	APR. C.F.Liao 20141224	PART NO. AS06600XXXXX2	DWG NO. AS06600XXXXX2
.xx± 0.25	.x'± 1'	CHK. Abel 20141224	UNITS: mm	
.xxx± 0.15	.xx'± 0.5'	DRAL. Michelle 20141224	CUSTOMER DRAWING	
		SIZE: A4	SCALE: FREE	SHEET 2 / 2
		REV: B0	V	

F

F